

## **AMENDMENTS TO THE CLAIMS**

Please amend Claim 1 as follows:

1. (Currently Amended) A cooling apparatus for a wafer baking plate having a support plate for supporting a wafer, a heater under the support plate, and a heat transfer plate interposed between the support plate and the heater, for transferring heat, comprising:

a hollow bore formed in the heat transfer plate and partially filled with a liquid working fluid; and

a cooling pipe laid along the hollow bore in the heat transfer plate, for circulating a cooling medium.

2. (Previously Presented) The cooling apparatus of claim 1, wherein the cooling pipe is laid in the hollow bore of the heat transfer plate and disposed in the working fluid which is liquid at room temperature.

3. (Previously Presented) The cooling apparatus of claim 1, wherein a groove is formed in the bottom of the hollow bore and the cooling pipe is laid in the groove.

4. (Previously Presented) The cooling apparatus of claim 1, wherein the cooling pipe is laid outside the hollow bore.

5. (Previously Presented) The cooling apparatus of claim 1, wherein the cooling pipe includes a first pipe laid in the hollow bore and a second pipe laid outside the hollow bore.

6. (Previously Presented) The cooling apparatus of claim 1, wherein a cross-section of the cooling pipe is one of circular, oval, and polygonal.